

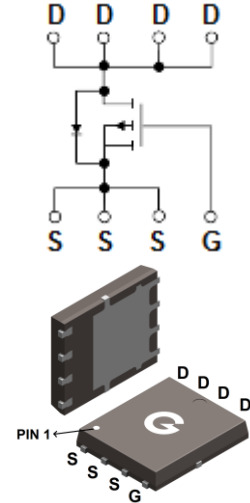
Features

- Advanced trench technology
- Low on-resistance
- Low gate charge
- HBM: AEC-Q101-001: H1B (JESD22-A114-B: 1B)
- RoHS compliant with Halogen-free
- Qualified to AEC-Q101 Standards

HF

Mechanical Data

- Case: PDFN5×6-8L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



PDFN5×6-8L

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TQBL100P04-5DL8	PDFN5×6-8L	5000 pcs / Tape & Reel	100P04

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	-40	V
Gate-to-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (T _C = 25°C)	I _D	-66	A
Continuous Drain Current (T _C = 100°C)		-47	A
Continuous Drain Current (T _A = 25°C) *1		-14	A
Continuous Drain Current (T _A = 100°C) *1		-10	A
Pulsed Drain Current (t _p = 10μs, T _C = 25°C)	I _{DM}	-264	A
Single Pulse Avalanche Energy *3	E _{AS}	130	mJ
Power Dissipation (T _C = 25°C)	P _D	83	W
Power Dissipation (T _A = 25°C) *1		3.75	
Operating Junction Temperature Range	T _J	-55 ~ +175	°C
Storage Temperature Range	T _{STG}	-55 ~ +175	°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	R _{θJC}	-	1.2	1.8	°C/W
Thermal Resistance Junction-to-Air *1	R _{θJA}	-	25	40	°C/W

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} = 0V	-	-	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance *2	V _{GS} = -10V,I _D = -15A	-	7.5	10	mΩ
		V _{GS} = -4.5V,I _D = -10A	-	9.5	15	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.7	-2.5	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	12.2	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V V _{DS} = -25V f = 1.0MHz	-	3286	-	pF
C _{OSS}	Output Capacitance		-	290	-	
C _{RSS}	Reverse Transfer Capacitance		-	193	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time *4	V _{DD} =-20V V _{GS} = -10V R _G = 3Ω R _L = 2Ω	-	16	-	ns
t _r	Turn-on Rise Time *4		-	41.8	-	
t _{d(OFF)}	Turn-Off Delay Time *4		-	173	-	
t _f	Turn-Off Fall Time *4		-	99	-	
Q _G	Total Gate-Charge	V _{DD} = -32V V _{GS} = -10V I _D = -15A	-	62	-	nC
Q _{GS}	Gate to Source Charge		-	12.3	-	
Q _{GD}	Gate to Drain (Miller) Charge		-	8.5	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage *2	I _{SD} = -15A, V _{GS} = 0V	-	-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} = -15A, V _{GS} = 0V di/dt = 100A/μs	-	66	-	ns
Q _{rr}	Reverse Recovery Charge		-	50	-	nC

Notes:

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
- The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The E_{AS} data shows Max. rating. The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.5mH$
- Guaranteed by design, not subject to production testing

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

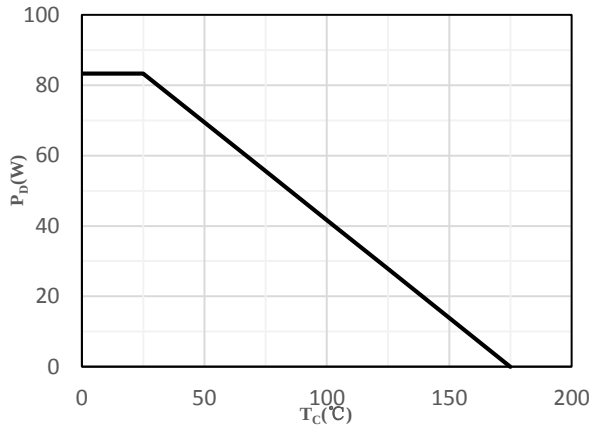


Fig 1 Power Dissipation

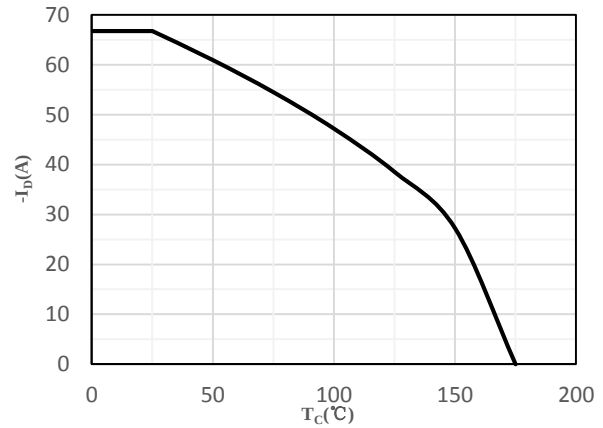


Fig 2 Drain Current

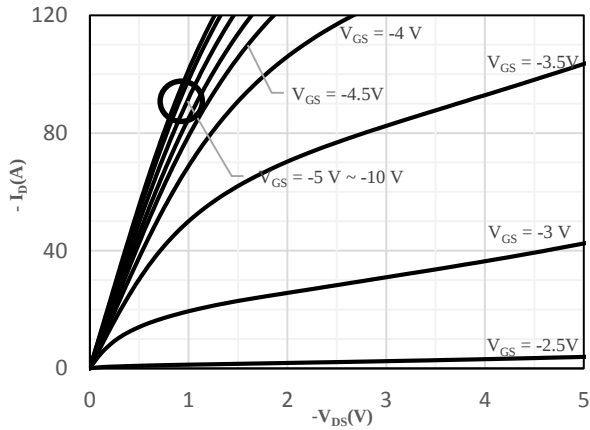


Fig 3 Typical Output Characteristics

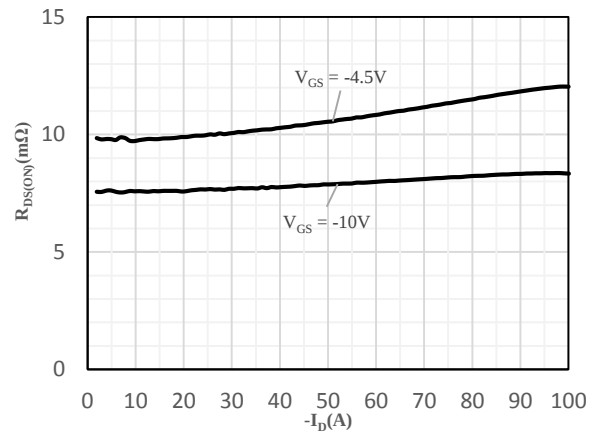


Fig 4 On-Resistance vs. Drain Current
and Gate Voltage

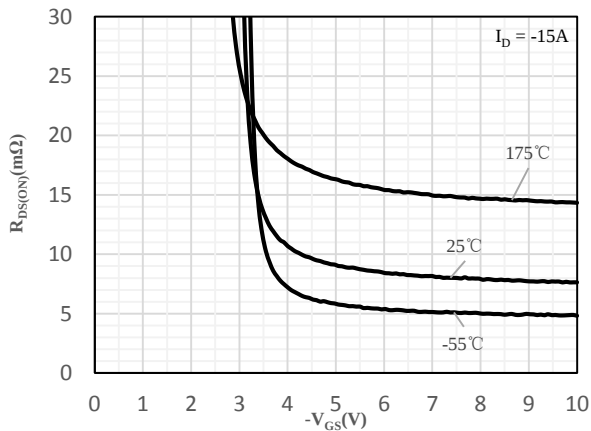


Fig 5 On-Resistance vs. Gate-Source Voltage

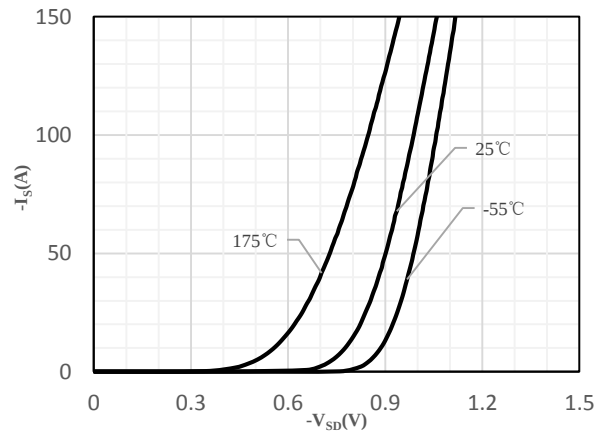


Fig 6 Body-Diode Characteristics

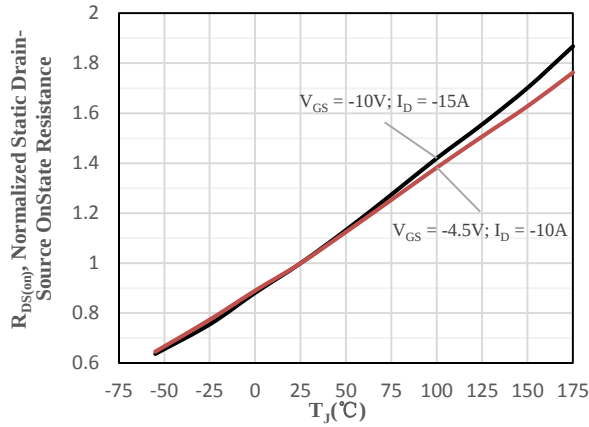


Fig 7 Normalized On-Resistance vs. Junction Temperature

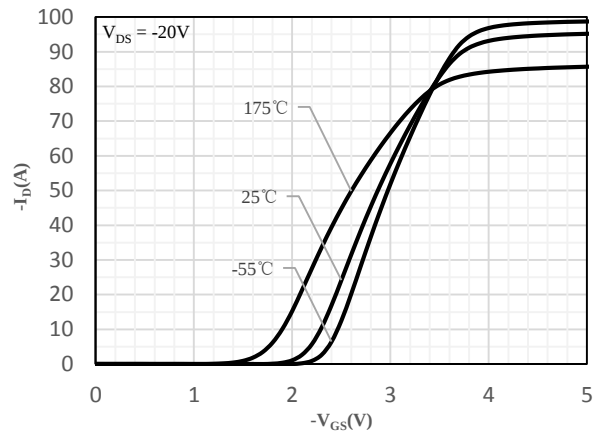


Fig 8 Transfer Characteristics

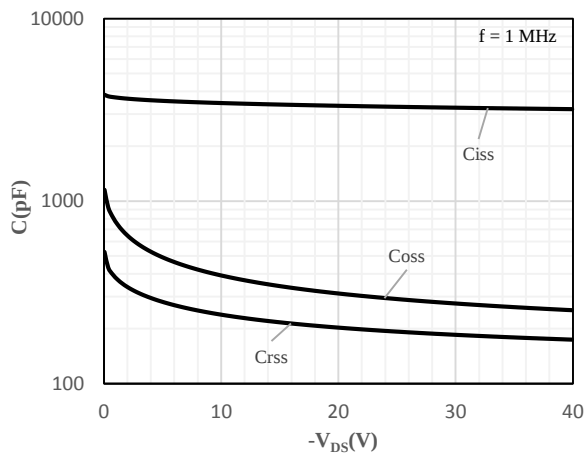


Fig 9 Capacitance Characteristics

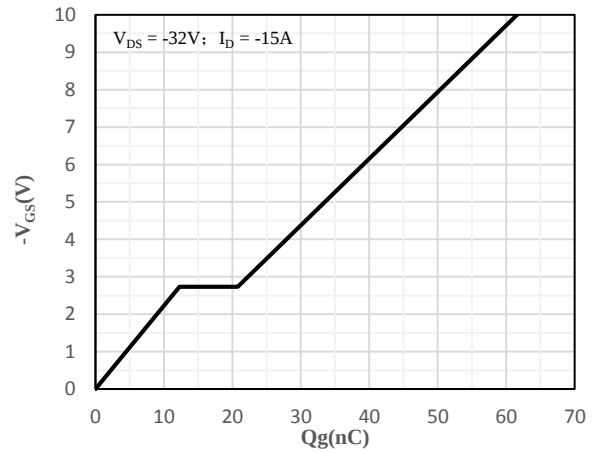


Fig 10 Gate-Charge Characteristics

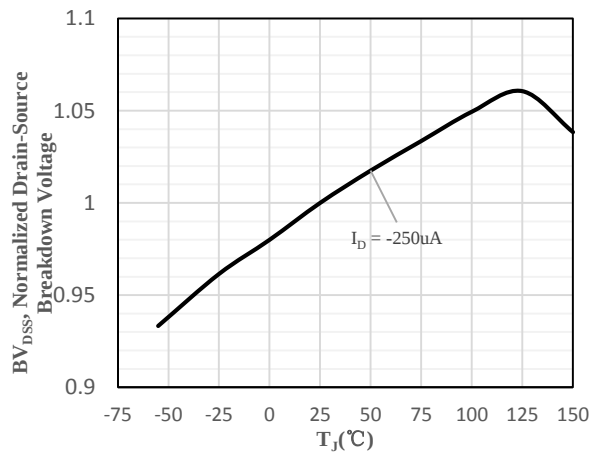


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

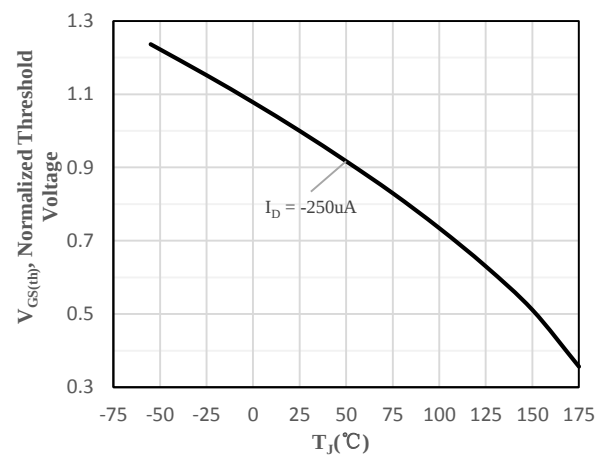


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

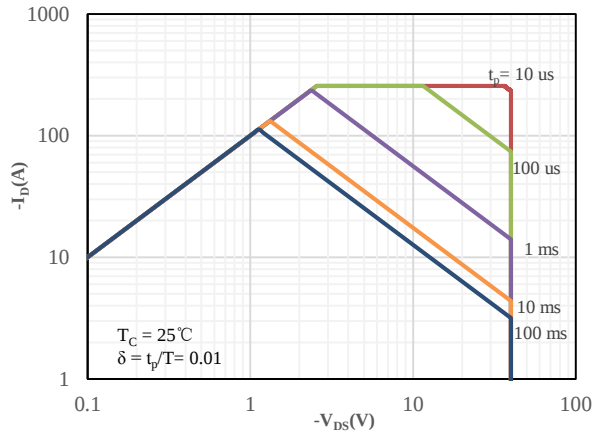


Fig 13 Safe Operating Area

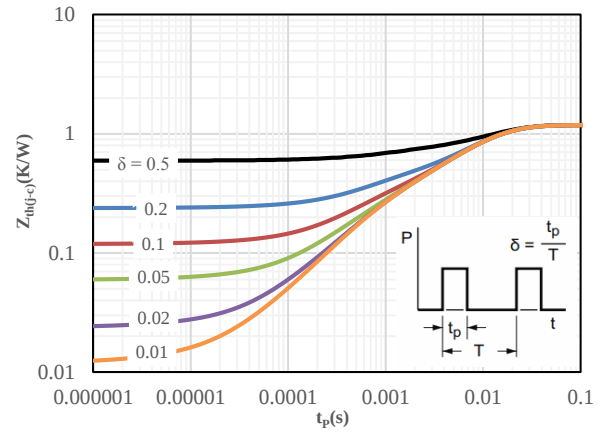
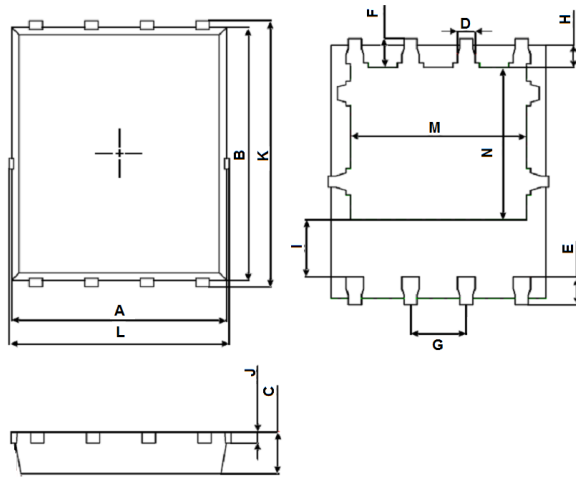


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



PDFN5x6-8L		
Dimension	Min.	Max.
A	4.824	4.976
B	5.674	5.826
C	0.900	1.000
D	0.350	0.450
E	0.559	0.711
F	0.574	0.726
G	1.250	1.290
H	0.424	0.576
I	1.190	1.390
J	0.154	0.354
K	5.974	6.126
L	4.944	5.096
M	3.910	4.110
N	3.375	3.575

Mounting Pad Layout (Unit: mm)

PDFN5x6-8L

